PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
OPA627AM	NRND	TO-99	LMC	8	20	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type
OPA627AP	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA627APG4	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA627AU	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA627AU/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA627AU/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA627AUE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA627AUG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA627BM	NRND	TO-99	LMC	8	20	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type
OPA627BP	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA627BPG4	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA627SM	NRND	TO-99	LMC	8	20	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type
OPA637AM	NRND	TO-99	LMC	8	20	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type
OPA637AM2	OBSOLETE	TO-99	LMC	8		TBD	Call TI	Call TI
OPA637AP	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA637APG4	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA637AU	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA637AU/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA637AU/2K5E4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA637AUE4	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
OPA637AUG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
OPA637BM	NRND	TO-99	LMC	8	20	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type
OPA637BM1	OBSOLETE	TO-99	LMC	8		TBD	Call TI	Call TI
OPA637BP	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA637BPG4	ACTIVE	PDIP	P	8	50	TBD	Call TI	Call TI
OPA637SM	NRND	TO-99	LMC	8	20	Green (RoHS & no Sb/Br)	AU	N / A for Pkg Type

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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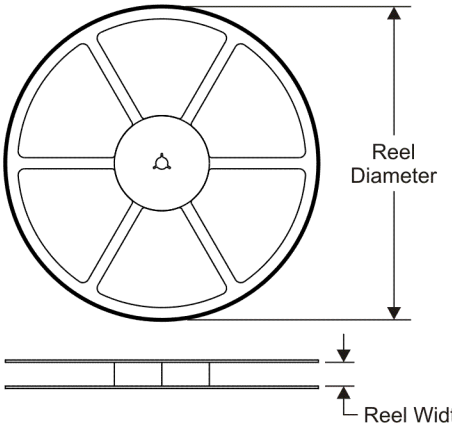
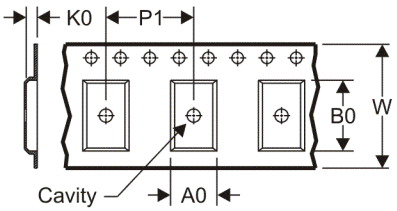
TAPE AND REEL INFORMATION

REEL DIMENSIONS

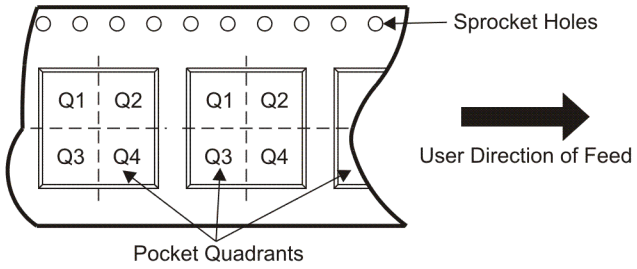


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

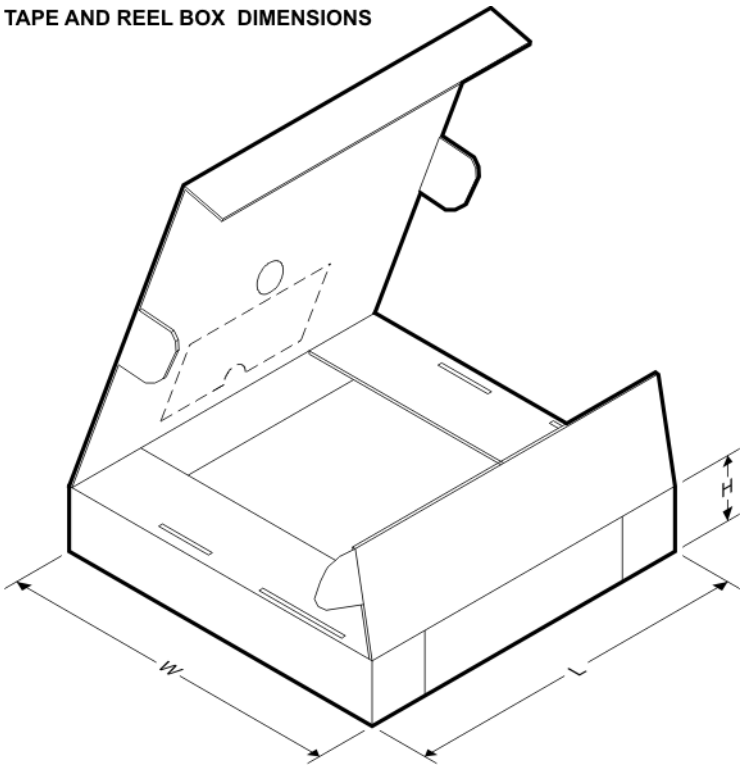
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA627AU/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA637AU/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA627AU/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA637AU/2K5	SOIC	D	8	2500	346.0	346.0	29.0

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